

Supplementary Information

Nanoparticle assembly by transient topography induced by applying soft lithography to block copolymer films

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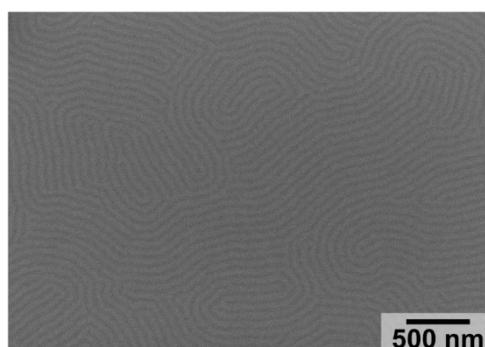


Fig. S1 SEM image of a chloroform vapour-annealed P2-b-P2VP film before stamping.

Fig. S2 shows the silicon mapping in the ridges and valleys of annealed films that have been subjected to chloroform vapour flattening for different intervals. Apart from the PDMS residue seen in the valleys (Fig. S2e-h and Fig. 5e-h), which were in direct contact with the stamp, a very thin layer rich with silicon and oxygen appears also on the ridges (Fig. S2a-d and Fig. 5a-d). The existence of PDMS on the ridges despite the lack of direct contact of these regions with the stamp can be explained by the low surface energy of PDMS, which may have driven some of the PDMS transferred from the stamp to “crawl” upward and cover the ridges during the stamping step.

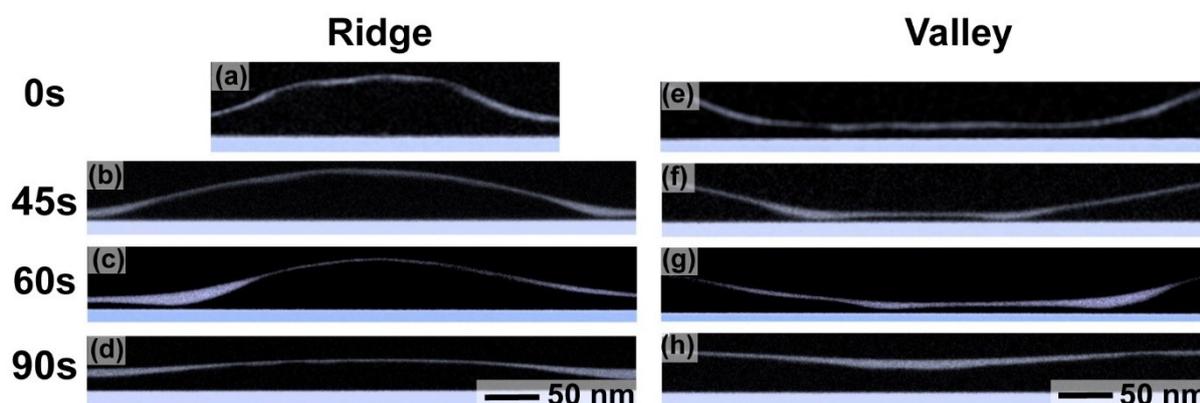


Fig. S2 Cross-sectional EDX mapping corresponding to Fig. 5, showing only the silicon mapping of ridges (a-d) and valleys (e-h) of annealed copolymer films stamped after chloroform vapour flattening for different intervals.

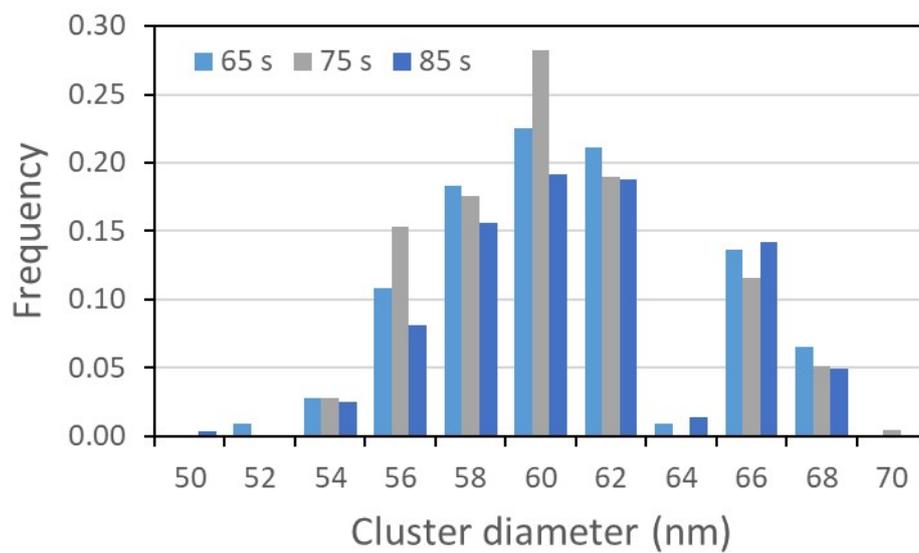


Fig. S3 Typical diameter histograms of NP clusters assembled after 65-85 s of chloroform vapour flattening.